



COPY OF PAPERS  
ORIGINALLY FILED

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

RECEIVED

Applicant(s): Tabrizi, B.  
Serial No.: 09/677,291  
Date Filed: October 2, 2000  
Invention: SEMICONDUCTOR PACKAGING  
Date: February 15, 2002

Atty. Dkt. 1920/107  
Art Unit: 2815  
Examiner: C. Chu

MAR 12 2002

TECHNOLOGY CENTER 2800

# 11/B  
3/26/2  
Juslen

\*\*\*\*\*

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231 on February 15, 2002.

  
Alexander Joseph Smolenski, Jr.

\*\*\*\*\*

Commissioner for Patents  
Washington, D.C. 20231

**Response to Outstanding Office Action**

Dear Sir:

In response to the Office Action mailed October 18, 2001, Applicant respectfully requests consideration of the following amendments and remarks.

**In the Claims:**

Please amend claims 2, 3, 7, 9, 14, 34, and 35 as follows:

*sub E1*  
*B1* 2. An electronic component according to claim 1, wherein:  
the conductive region is formed by metallization.

3. An electronic component according to claim 2, wherein:  
the metallization is achieved through a deposition process.

*B2*  
*sub E1* 7. An electronic component according to claim 1, further comprising: